




# Power MOSFETS


## DATASHEET

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**LM60016NHM8A**

N-Channel  
Enhancement Mode MOSFET

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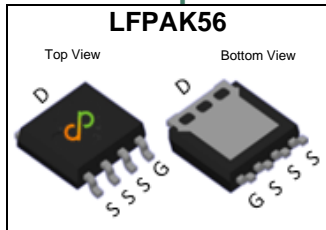


Quality Management Systems

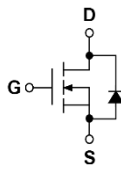
ISO 9001:2015 Certificate

## N-Channel Enhancement Mode MOSFET

### Pin Description



### Symbol



### Product Summary

Symbol	N-Channel	Unit
$V_{DSS}$	60	V
$R_{DS(ON)-Max}$	1.55	m $\Omega$
ID	259	A

### Feature

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

### Applications

- Synchronous Rectification in SMPS

### Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM60016NHM8A	LFPAK56	Tape & Reel	4000 / Tape & Reel	60016 □□□□□□

Note : □□□□□□ = Lot Code

### Absolute Maximum Ratings (T<sub>J</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit
$V_{DSS}$	Drain-Source Voltage	60	V
$V_{GSS}$	Gate-Source Voltage	±20	
$T_J$	Maximum Junction Temperature	150	°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ C$ 82	A
$I_{DM}^{(1)}$	Pulse Drain Current Tested	$T_C=25^\circ C$ 400	A
$I_D$	Continuous Drain Current	$T_C=25^\circ C$ 259	A
		$T_C=100^\circ C$ 164	
$P_D$	Maximum Power Dissipation	$T_C=25^\circ C$ 104	W
		$T_C=100^\circ C$ 42	
$I_D$	Continuous Drain Current	$T_A=25^\circ C$ 42	A
		$T_A=70^\circ C$ 34	
$P_D$	Maximum Power Dissipation	$T_A=25^\circ C$ 2.8	W
		$T_A=70^\circ C$ 1.8	
$I_{AS}^{(2)}$	Avalanche Current, Single pulse	L=0.1mH 60	A
		L=0.5mH 31	
$E_{AS}^{(2)}$	Avalanche Energy, Single pulse	L=0.1mH 180	mJ
		L=0.5mH 240	

### Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	1.2 °C/W
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	Steady State	45 °C/W

Note ① : Max. current is limited by bonding wire

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in<sup>2</sup> FR-4 board with 1oz

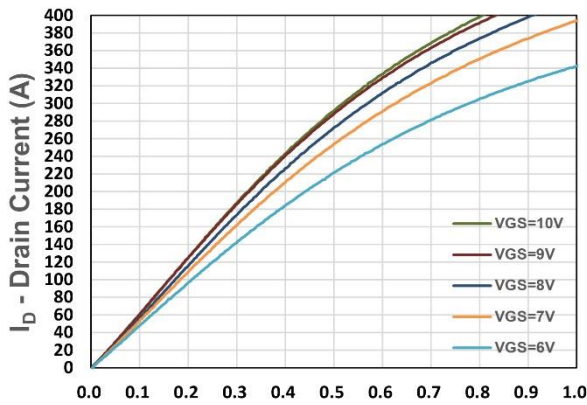
## N-Channel Electrical Characteristics (T<sub>J</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics</b>						
<b>BV<sub>DSS</sub></b>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250uA	60	-	-	V
<b>I<sub>DSS</sub></b>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V	-	-	1	uA
<b>V<sub>GS(th)</sub></b>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250uA	2	2.5	4	V
<b>I<sub>GSS</sub></b>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>R<sub>DS(ON)</sub><sup>④</sup></b>	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =20A	-	1.25	1.55	mΩ
<b>gfs</b>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>DS</sub> =20A	-	75	-	S
<b>Dynamic Characteristics<sup>⑤</sup></b>						
<b>R<sub>G</sub></b>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, Freq.=1MHz	-	1.6	-	Ω
<b>C<sub>iSS</sub></b>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =30V, Freq.=1MHz	-	4805	-	pF
<b>C<sub>oss</sub></b>	Output Capacitance		-	1372	-	
<b>C<sub>rSS</sub></b>	Reverse Transfer Capacitance		-	68	-	
<b>t<sub>d(ON)</sub></b>	Turn-on Delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =30V, I <sub>D</sub> =20A, R <sub>GEN</sub> =10Ω	-	20	-	nS
<b>t<sub>r</sub></b>	Turn-on Rise Time		-	16	-	
<b>t<sub>d(OFF)</sub></b>	Turn-off Delay Time		-	40	-	
<b>t<sub>f</sub></b>	Turn-off Fall Time		-	15	-	
<b>Q<sub>g</sub></b>	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =30V, I <sub>D</sub> =20A	-	85	-	nC
<b>Q<sub>gs</sub></b>	Gate-Source Charge		-	16	-	
<b>Q<sub>gd</sub></b>	Gate-Drain Charge		-	20	-	
<b>Source-Drain Characteristics</b>						
<b>V<sub>SD</sub><sup>④</sup></b>	Diode Forward Voltage	I <sub>SD</sub> =20A, V <sub>GS</sub> =0V	-	0.9	1.2	V
<b>t<sub>rr</sub></b>	Reverse Recovery Time	I <sub>F</sub> =20A, V <sub>R</sub> =30V	-	65	-	nS
<b>Q<sub>rr</sub></b>	Reverse Recovery Charge	dI <sub>F</sub> /dt=100A/μs	-	79	-	nC

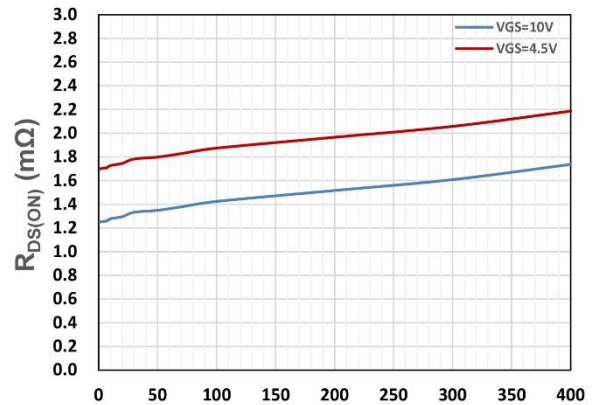
Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

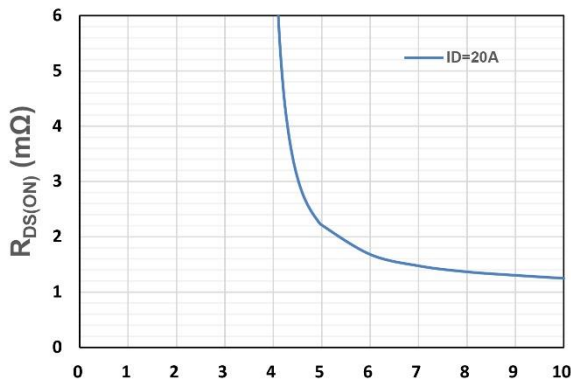
## N-Channel Typical Characteristics



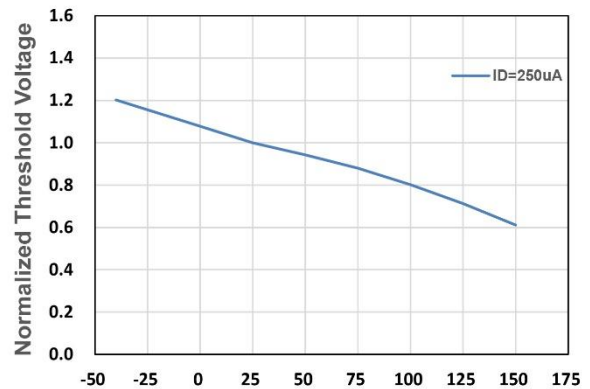
$V_{DS}$  - Drain - Source Voltage (V)  
Figure 1. Output Characteristics



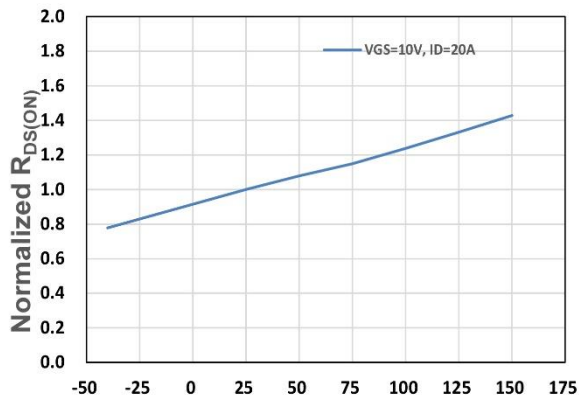
$I_D$  - Drain Current (A)  
Figure 2. On-Resistance vs.  $I_D$



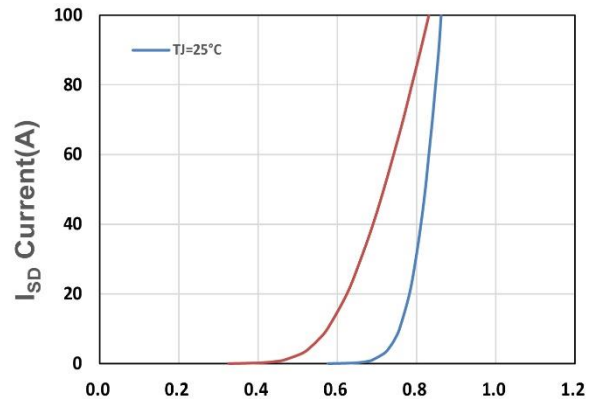
$V_{GS}$  - Gate - Source Voltage (V)  
Figure 3. On-Resistance vs.  $V_{GS}$



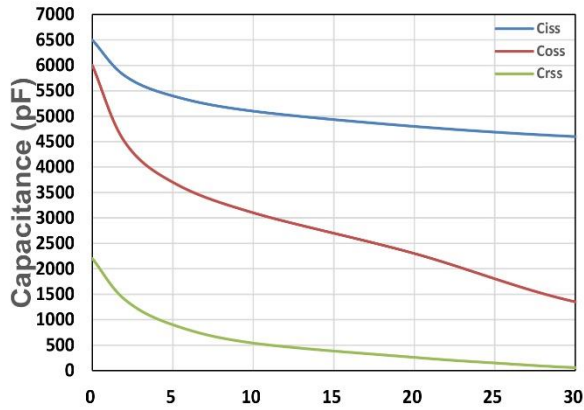
$T_j$ , Junction Temperature( $^{\circ}C$ )  
Figure 4. Gate Threshold Voltage



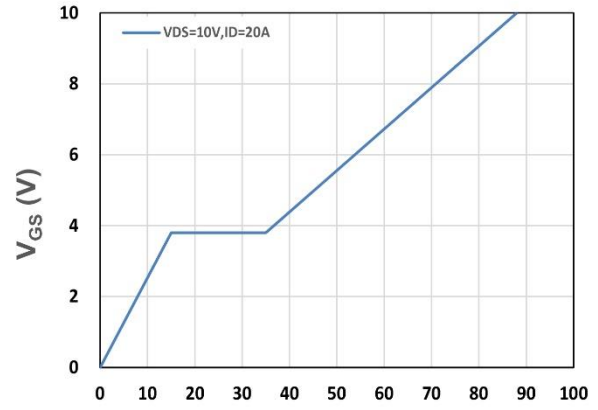
$T_j$ , Junction Temperature( $^{\circ}C$ )  
Figure 5. Drain-Source On Resistance



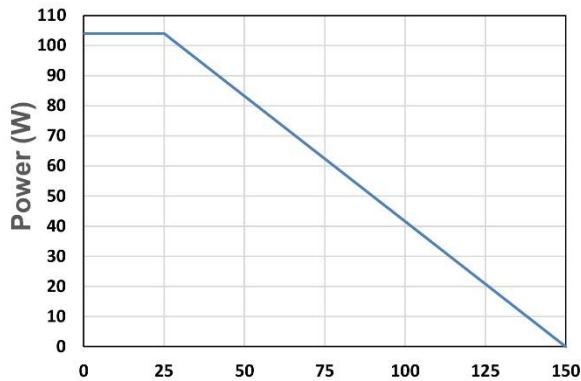
$V_{SD}$ , Source-Drain Voltage(V)  
Figure 6. Source-Drain Diode Forward



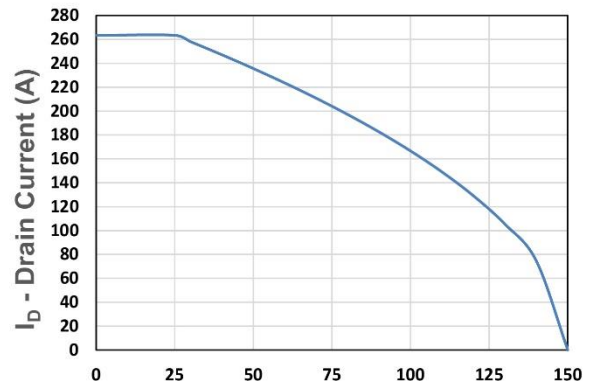
$V_{DS}$  - Drain - Source Voltage (V)  
Figure 7. Capacitance



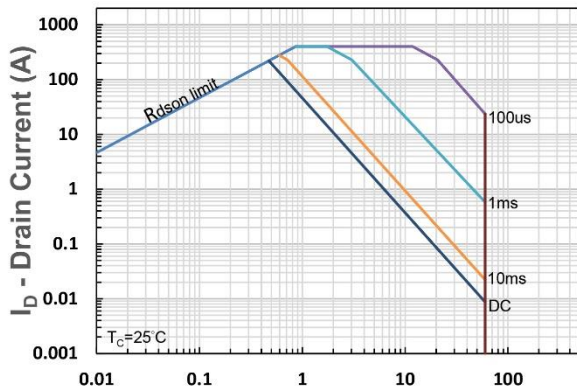
$Q_g$ , Total Gate Charge (nC)  
Figure 8. Gate Charge Characteristics



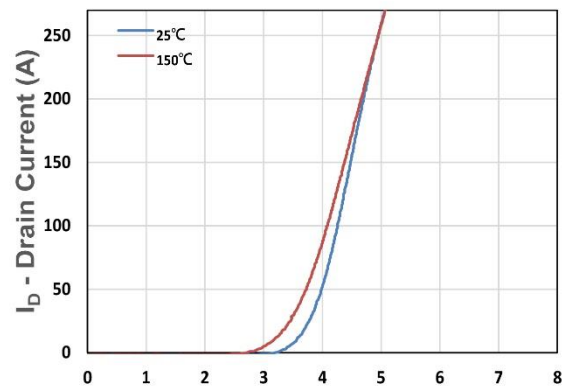
$T_c$  - Case Temperature ( $^{\circ}C$ )  
Figure 9. Power Dissipation



$T_c$  - Case Temperature ( $^{\circ}C$ )  
Figure 10. Drain Current



$V_{DS}$  - Drain-Source Voltage (V)  
Figure 11. Safe Operating Area



$V_{GS}$  - Gate - Source Voltage (V)  
Figure 12. Transfer Characteristics

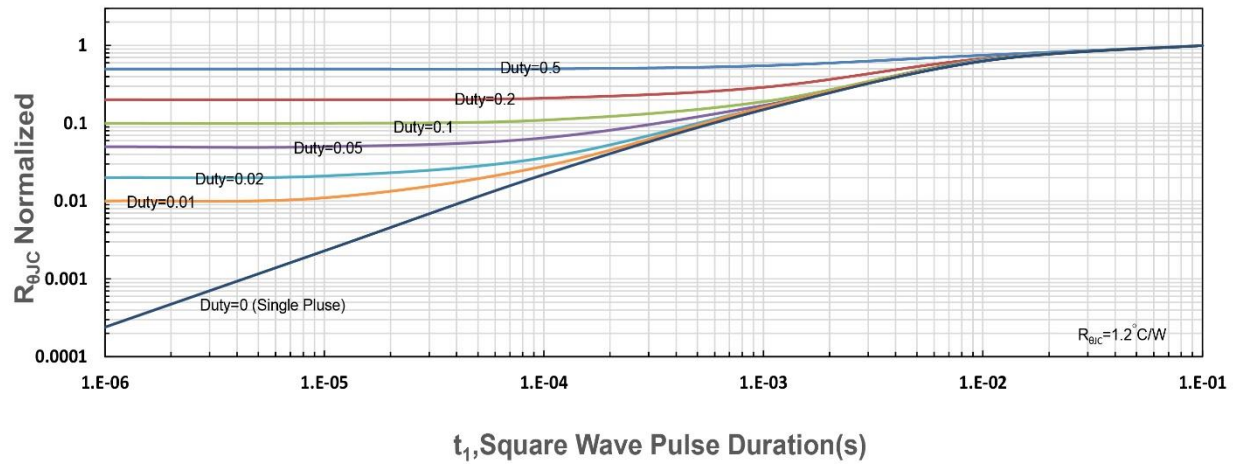


Figure 13.  $R_{\theta JC}$  Transient Thermal Impedance